

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) An interconnect substrate over which an interconnect pattern is formed, comprising:
  - a first portion; and
  - a second portion ~~to be superposed on the first portion,~~
  - wherein the first portion has end parts as positioning references; and
  - wherein the second portion has such a shape so as to be that when the interconnect substrate is folded only at one boundary of the first and second portions, the second portion is superposed on and inside the first portion except the end parts, the second portion and is positioned between the end parts.
2. (Previously Amended) The interconnect substrate as defined in claim 1,
  - wherein each of the end parts as the positioning references includes two edges which are perpendicular to each other.
3. (Previously Amended) The interconnect substrate as defined in claim 1,
  - wherein the first portion comprises a rectangular body section and a projected section which extends from at least one edge of the body section and includes one of the end parts.
4. (Previously Amended) The interconnect substrate as defined in claim 3,
  - wherein the projected section is a region determined by:
    - an edge which is a boundary between the projected section and the body section;
    - a first edge which is perpendicular to the edge as a boundary; and
    - a second top edge which is parallel to the edge as a boundary,
  - wherein one of the end parts as the positioning references includes the first and second edges.

5. (Original) The interconnect substrate as defined in claim 4,  
wherein the body section of the first portion includes an edge having no projected  
section; and  
wherein the second portion is disposed adjacent to the edge having no projected  
section.
6. (Original) The interconnect substrate as defined in claim 4,  
wherein the second portion has a depressed section facing the projected section of  
the first portion.
7. (Previously Amended) The interconnect substrate as defined in claim 6,  
wherein at least one of the end parts is formed from an area in the body section other  
than an area from which the projected section extends.
8. (Original) The interconnect substrate as defined in claim 2,  
wherein the first portion is larger than the second portion; and  
wherein the two edges which are perpendicular to each other form a corner section  
of the first portion.
9. (Original) The interconnect substrate as defined in claim 2,  
wherein the first portion has a depressed end part including the two edges which are  
perpendicular to each other and have an right angle.
10. (Previously Amended) The interconnect substrate as defined in claim 1,  
wherein a plurality of holes are formed in the end parts.
11. (Previously Amended) The interconnect substrate as defined in claim 1,  
wherein the second portion continuously extends from the first portion.
12. (Previously Amended) The interconnect substrate as defined in claim 1,  
wherein the second portion is separated from the first portion; and  
wherein the first and second portions are connected by the interconnect pattern.

13. (Currently Amended) A semiconductor device comprising:

at least one semiconductor chip; and

~~a substrate which has a first portion and a second portion to be superposed on the first portion, and on which the semiconductor chip is mounted, the substrate having a first portion including end parts as positioning references, the substrate having a second portion, the substrate folded at one boundary of the first and second portions to superpose the second portion on and inside the first portion except the end parts, the second portion positioned between the end parts, wherein the first portion includes end parts as positioning references; and~~

wherein the second portion has a shape so as to be superposed on and inside the first portion and ~~avoid being superposed over except the end parts of the first portion by folding the substrate only at the one boundary of the first and second portions, the second portion positioned between the end parts.~~

14. (Original) The semiconductor device as defined in claim 13,

wherein a plurality of external terminals are provided in the first portion.

15. (Previously Amended) The semiconductor device as defined in claim 13,

wherein the interconnect substrate as defined in claim 1 is used as the substrate.

16. (Previously Amended) A circuit board on which is mounted the semiconductor device as defined in claim 13.

17. (Previously Amended) An electronic instrument provided with the semiconductor device as defined in claim 13.

18. (Previously Amended) A method of fabricating a semiconductor device, comprising the steps of:

mounting at least one semiconductor chip over the interconnect substrate as defined in claim 1; and

superposing the second portion on the first portion of the interconnect substrate.

19. (Previously Amended) A method of inspecting a semiconductor device, comprising the steps of:

positioning the semiconductor device as defined in claim 13 by using the end parts as the positioning references; and

inspecting electrical characteristics of the semiconductor device.

20. (Previously Amended) A method of mounting a semiconductor device comprising the steps of:

positioning the semiconductor device as defined in claim 13 by using the end parts as the positioning references; and

mounting the semiconductor device on a circuit board.

---